



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC50N08S5N102	Issued	11. August 2021
MA#	MA005430855		
Package	PG-TDSON-8-33	Weight*	111.51 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.510	0.46	0.46	4569	4569
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	iron	7439-89-6	0.053	0.05		474	
	non noble metal	copper	7440-50-8	52.842	47.38	47.44	473870	474486
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	398	398
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		688	
	plastics	epoxy resin	-	6.062	5.44		54360	
	inorganic material	silicondioxide	60676-86-0	32.227	28.90	34.41	289002	344050
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14113	14113
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1876	1876
solder	non noble metal	tin	7440-31-5	0.015	0.01		133	
	noble metal	silver	7440-22-4	0.018	0.02		166	
	non noble metal	lead	7439-92-1	0.706	0.63	0.66	6329	6628
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.09	15.11	150904	151100
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2776	2780
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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